



# PMV27UPE

20 V, P-channel Trench MOSFET

15 May 2014

Product data sheet

## 1. General description

P-channel enhancement mode Field-Effect Transistor (FET) in a small SOT23 (TO-236AB) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

## 2. Features and benefits

- Trench MOSFET technology
- Low threshold voltage
- Very fast switching
- Enhanced power dissipation capability:  $P_{tot} = 980$  mW
- ElectroStatic Discharge (ESD) protection 2 kV HBM

## 3. Applications

- LED driver
- Power management
- High-side loadswitch
- Switching circuits

## 4. Quick reference data

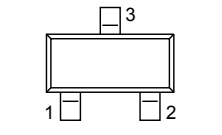
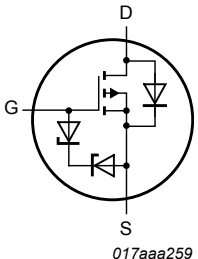
Table 1. Quick reference data

| Symbol                        | Parameter                        | Conditions   | Min | Typ | Max  | Unit |
|-------------------------------|----------------------------------|--|-----|-----|------|------|
| $V_{DS}$                      | drain-source voltage             | $T_j = 25$ °C                                      | -   | -   | -20  | V    |
| $V_{GS}$                      | gate-source voltage              |  | -8  | -   | 8    | V    |
| $I_D$                         | drain current                    | $V_{GS} = -4.5$ V; $T_{amb} = 25$ °C; $t \leq 5$ s | [1] | -   | -5.6 | A    |
| <b>Static characteristics</b> |                                  |  |     |     |      |      |
| $R_{DSon}$                    | drain-source on-state resistance | $V_{GS} = -4.5$ V; $I_D = -4.5$ A; $T_j = 25$ °C   | -   | 27  | 32   | mΩ   |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm<sup>2</sup>.

## 5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline  | Graphic symbol   |
|-----|--------|-------------|---|--|
| 1   | G      | gate        | <br>TO-236AB (SOT23) | <br>017aaa259 |
| 2   | S      | source      |   |  |
| 3   | D      | drain       |   |  |

## 6. Ordering information

Table 3. Ordering information

| Type number | Package  |  |         |
|-------------|----------|--|---------|
|             | Name     | Description                              | Version |
| PMV27UPE    | TO-236AB | plastic surface-mounted package; 3 leads | SOT23   |

## 7. Marking

Table 4. Marking codes

| Type number | Marking code |
|-------------|--------------|
| PMV27UPE    | %KD          |

[1] % = placeholder for manufacturing site code

## 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol    | Parameter               | Conditions   |     | Min | Max  | Unit |
|-----------|-------------------------|--|-----|-----|------|------|
| $V_{DS}$  | drain-source voltage    | $T_j = 25\text{ °C}$   |     | -   | -20  | V    |
| $V_{GS}$  | gate-source voltage     |  |     | -8  | 8    | V    |
| $I_D$     | drain current           | $V_{GS} = -4.5\text{ V}; T_{amb} = 25\text{ °C}; t \leq 5\text{ s}$      | [1] | -   | -5.6 | A    |
|           |                         | $V_{GS} = -4.5\text{ V}; T_{amb} = 25\text{ °C}$                         | [1] | -   | -4.5 | A    |
|           |                         | $V_{GS} = -4.5\text{ V}; T_{amb} = 100\text{ °C}$                        | [1] | -   | -2.8 | A    |
| $I_{DM}$  | peak drain current      | $T_{amb} = 25\text{ °C};$ single pulse; $t_p \leq 10\text{ }\mu\text{s}$ |     | -   | -18  | A    |
| $P_{tot}$ | total power dissipation | $T_{amb} = 25\text{ °C}$   | [2] | -   | 490  | mW   |

| Symbol                    | Parameter            | Conditions               |     | Min | Max  | Unit |
|---------------------------|----------------------|--------------------------|-----|-----|------|------|
|                           |                      |                          | [1] | -   | 980  | mW   |
|                           |                      | T <sub>sp</sub> = 25 °C  |     | -   | 4150 | mW   |
| T <sub>j</sub>            | junction temperature |                          |     | -55 | 150  | °C   |
| T <sub>amb</sub>          | ambient temperature  |                          |     | -55 | 150  | °C   |
| T <sub>stg</sub>          | storage temperature  |                          |     | -65 | 150  | °C   |
| <b>Source-drain diode</b> |                      |                          |     |     |      |      |
| I <sub>s</sub>            | source current       | T <sub>amb</sub> = 25 °C | [1] | -   | -1.2 | A    |

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm<sup>2</sup>.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

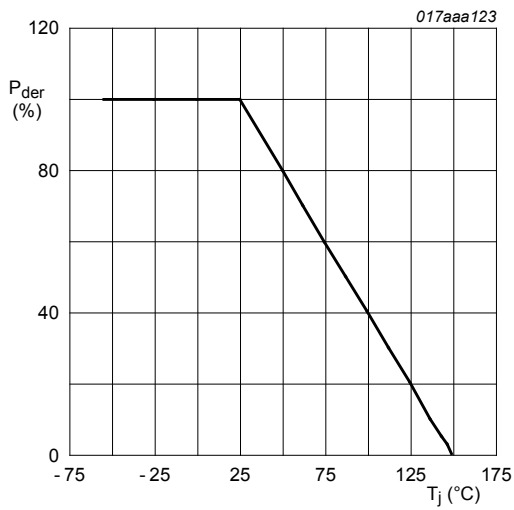


Fig. 1. Normalized total power dissipation as a function of junction temperature

$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}\text{C})}} \times 100 \%$$

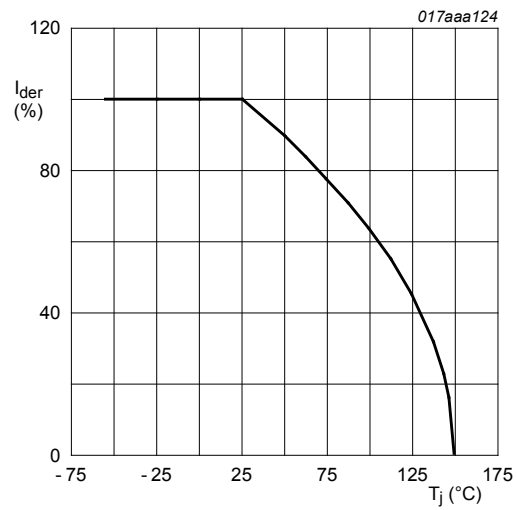
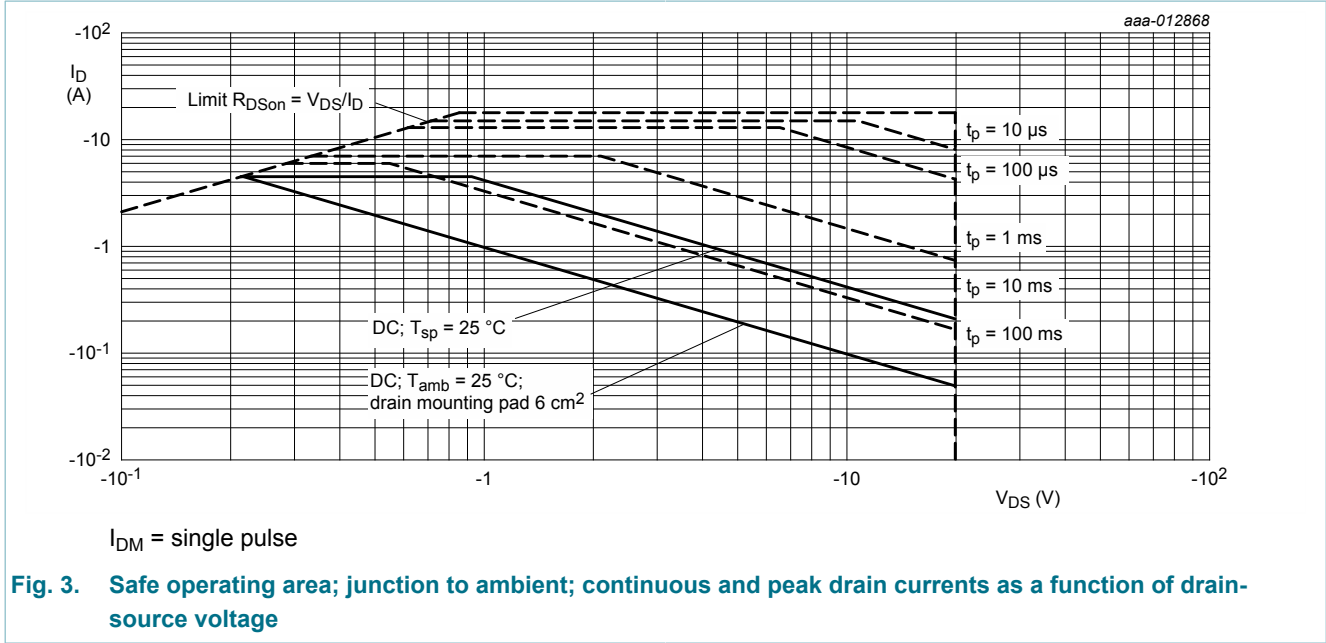


Fig. 2. Normalized continuous drain current as a function of junction temperature

$$I_{der} = \frac{I_D}{I_{D(25^{\circ}\text{C})}} \times 100 \%$$



## 9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol         | Parameter  | Conditions                        |     | Min | Typ | Max | Unit |
|----------------|--|-----------------------------------|-----|-----|-----|-----|------|
| $R_{th(j-a)}$  | thermal resistance from junction to ambient      | in free air                       | [1] | -   | 222 | 255 | K/W  |
|                |  |                                   | [2] | -   | 111 | 128 | K/W  |
|                |  | in free air; $t \leq 5 \text{ s}$ | [2] | -   | 74  | 85  | K/W  |
| $R_{th(j-sp)}$ | thermal resistance from junction to solder point |                                   |     | -   | 25  | 30  | K/W  |

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain  $6 \text{ cm}^2$ .

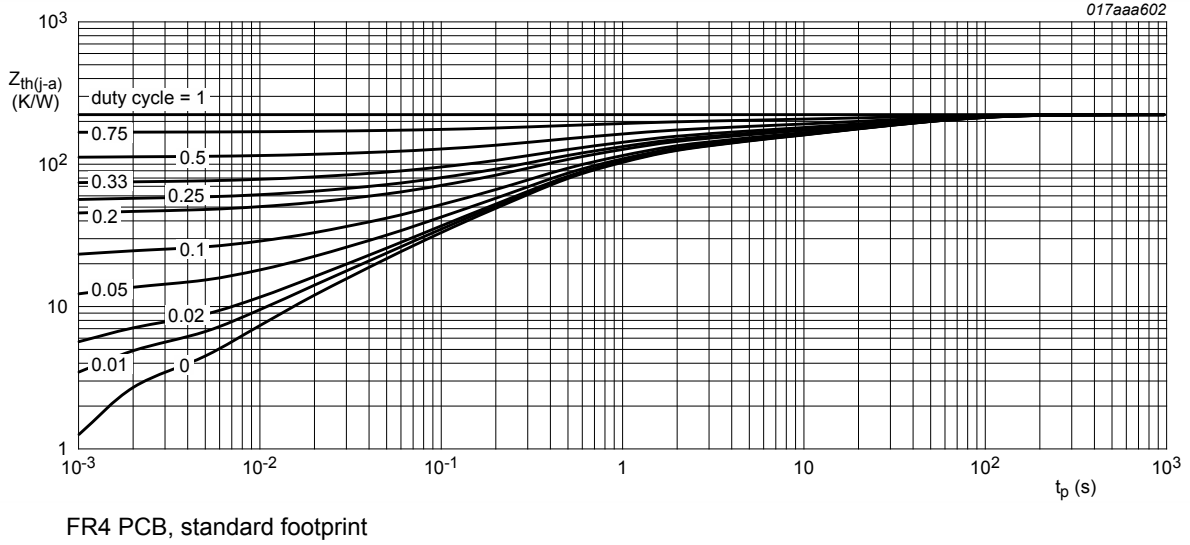


Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

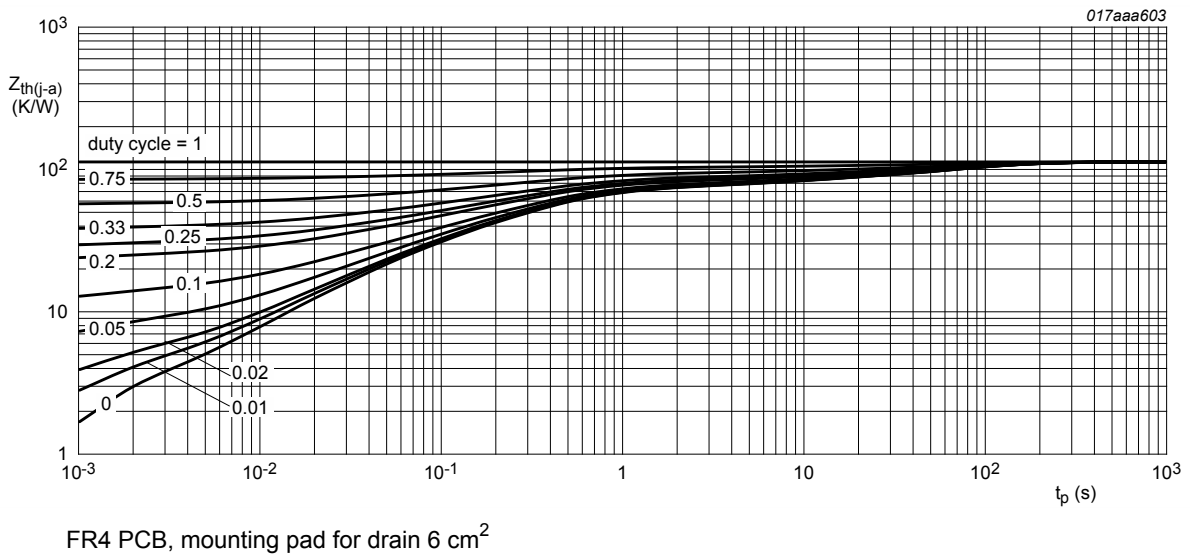


Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 10. Characteristics

Table 7. Characteristics

| Symbol                         | Parameter                        | Conditions   | Min   | Typ  | Max   | Unit       |
|--------------------------------|----------------------------------|--|-------|------|-------|------------|
| <b>Static characteristics</b>  |                                  |  |       |      |       |            |
| $V_{(BR)DSS}$                  | drain-source breakdown voltage   | $I_D = -250 \mu A$ ; $V_{GS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$  | -20   | -    | -     | V          |
| $V_{GSth}$                     | gate-source threshold voltage    | $I_D = -250 \mu A$ ; $V_{DS} = V_{GS}$ ; $T_j = 25 \text{ }^\circ C$   | -0.45 | -0.7 | -0.95 | V          |
| $I_{DSS}$                      | drain leakage current            | $V_{DS} = -20 V$ ; $V_{GS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$  | -     | -    | -1    | $\mu A$    |
| $I_{GSS}$                      | gate leakage current             | $V_{GS} = 8 V$ ; $V_{DS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$  | -     | -    | 10    | $\mu A$    |
|                                |                                  | $V_{GS} = -8 V$ ; $V_{DS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$   | -     | -    | -10   | $\mu A$    |
|                                |                                  | $V_{GS} = 4.5 V$ ; $V_{DS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$  | -     | -    | 5     | $\mu A$    |
|                                |                                  | $V_{GS} = -4.5 V$ ; $V_{DS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$   | -     | -    | -5    | $\mu A$    |
| $R_{DSon}$                     | drain-source on-state resistance | $V_{GS} = -4.5 V$ ; $I_D = -4.5 A$ ; $T_j = 25 \text{ }^\circ C$   | -     | 27   | 32    | m $\Omega$ |
|                                |                                  | $V_{GS} = -4.5 V$ ; $I_D = -4.5 A$ ; $T_j = 150 \text{ }^\circ C$  | -     | 40   | 48    | m $\Omega$ |
|                                |                                  | $V_{GS} = -2.5 V$ ; $I_D = -3.8 A$ ; $T_j = 25 \text{ }^\circ C$   | -     | 38   | 45    | m $\Omega$ |
|                                |                                  | $V_{GS} = -1.8 V$ ; $I_D = -3 A$ ; $T_j = 25 \text{ }^\circ C$   | -     | 50   | 63    | m $\Omega$ |
| $g_{fs}$                       | forward transconductance         | $V_{DS} = -10 V$ ; $I_D = -2 A$ ; $T_j = 25 \text{ }^\circ C$  | -     | 15   | -     | S          |
| $R_G$                          | gate resistance                  | $f = 1 \text{ MHz}$  | -     | 10.7 | -     | $\Omega$   |
| <b>Dynamic characteristics</b> |                                  |  |       |      |       |            |
| $Q_{G(tot)}$                   | total gate charge                | $V_{DS} = -10 V$ ; $I_D = -4.4 A$ ; $V_{GS} = -4.5 V$ ;<br>$T_j = 25 \text{ }^\circ C$                           | -     | 14.7 | 22.1  | nC         |
| $Q_{GS}$                       | gate-source charge               |  | -     | 2.6  | -     | nC         |
| $Q_{GD}$                       | gate-drain charge                |  | -     | 2.5  | -     | nC         |
| $C_{iss}$                      | input capacitance                | $V_{DS} = -10 V$ ; $f = 1 \text{ MHz}$ ; $V_{GS} = 0 V$ ;<br>$T_j = 25 \text{ }^\circ C$                         | -     | 1820 | -     | pF         |
| $C_{oss}$                      | output capacitance               |  | -     | 208  | -     | pF         |
| $C_{riss}$                     | reverse transfer capacitance     |  | -     | 146  | -     | pF         |
| $t_{d(on)}$                    | turn-on delay time               | $V_{DS} = -10 V$ ; $I_D = -4.4 A$ ; $V_{GS} = -4.5 V$ ;<br>$R_{G(ext)} = 6 \Omega$ ; $T_j = 25 \text{ }^\circ C$ | -     | 11   | -     | ns         |
| $t_r$                          | rise time                        |  | -     | 30   | -     | ns         |
| $t_{d(off)}$                   | turn-off delay time              |  | -     | 83   | -     | ns         |
| $t_f$                          | fall time                        |  | -     | 39   | -     | ns         |
| <b>Source-drain diode</b>      |                                  |  |       |      |       |            |
| $V_{SD}$                       | source-drain voltage             | $I_S = -1.2 A$ ; $V_{GS} = 0 V$ ; $T_j = 25 \text{ }^\circ C$  | -     | -0.7 | -1.2  | V          |

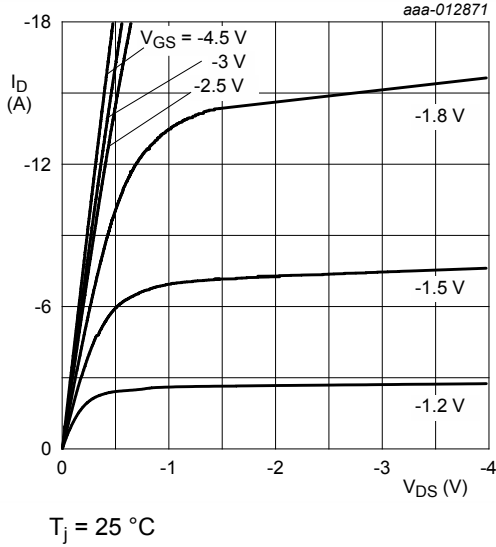


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

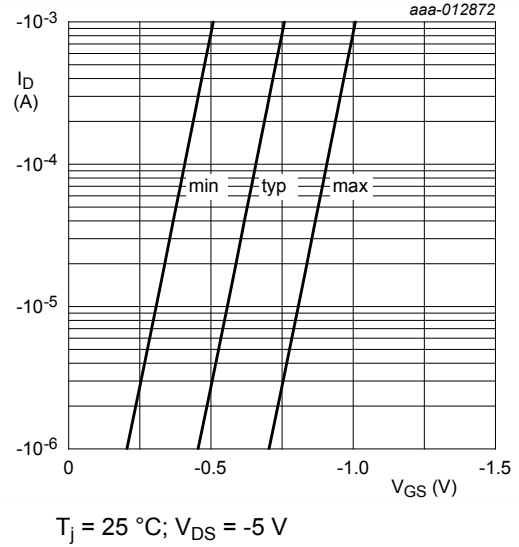


Fig. 7. Sub-threshold drain current as a function of gate-source voltage

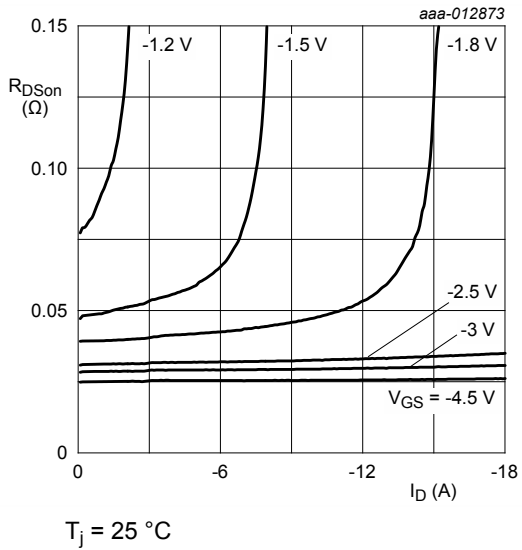


Fig. 8. Drain-source on-state resistance as a function of drain current; typical values

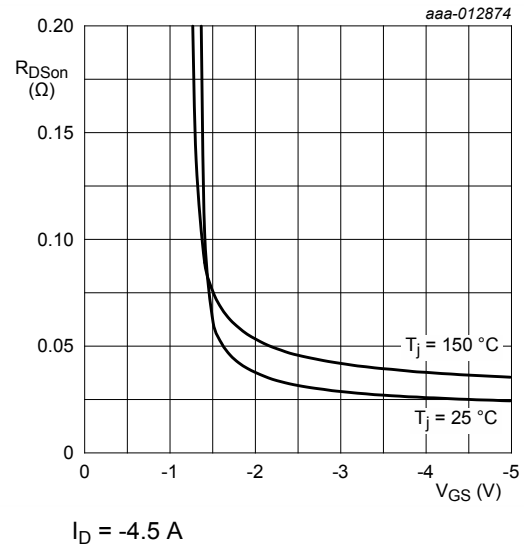
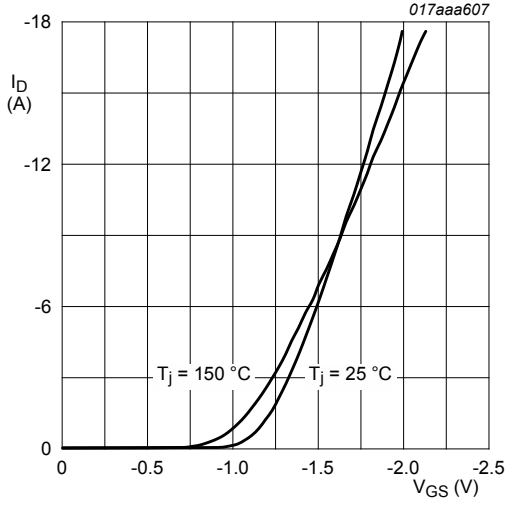
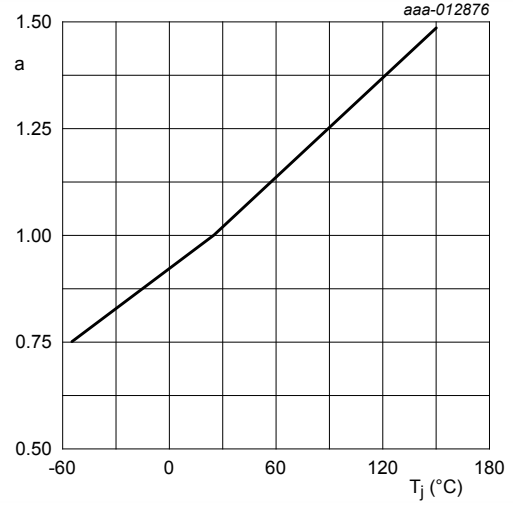


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values



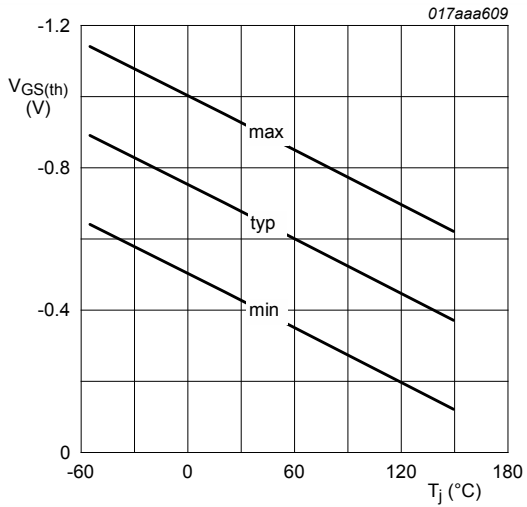
$$V_{DS} > I_D \times R_{DSon}$$

**Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values**



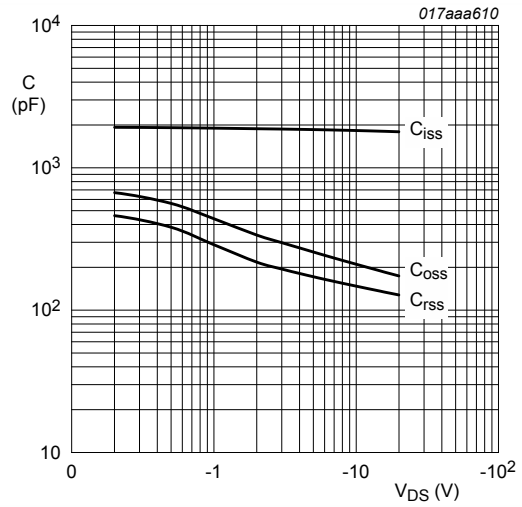
**Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values**

$$a = \frac{R_{DSon}}{R_{DSon(25^\circ C)}}$$



$$I_D = -0.25 \text{ mA}; V_{DS} = V_{GS}$$

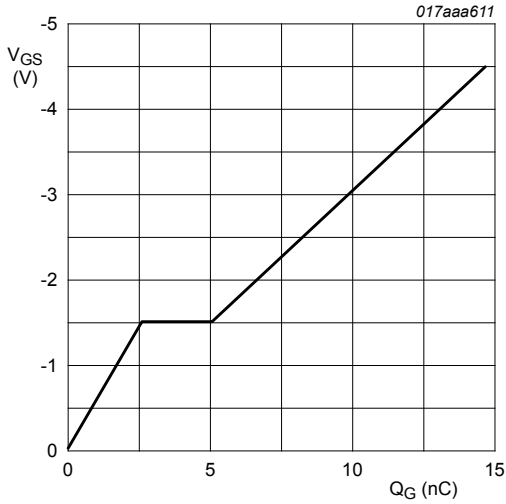
**Fig. 12. Gate-source threshold voltage as a function of junction temperature**



$$f = 1 \text{ MHz}; V_{GS} = 0 \text{ V}$$

**Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values**





$I_D = -4.4 \text{ A}; V_{DS} = -10 \text{ V}; T_{amb} = 25 \text{ }^\circ\text{C}$

Fig. 14. Gate-source voltage as a function of gate charge; typical values

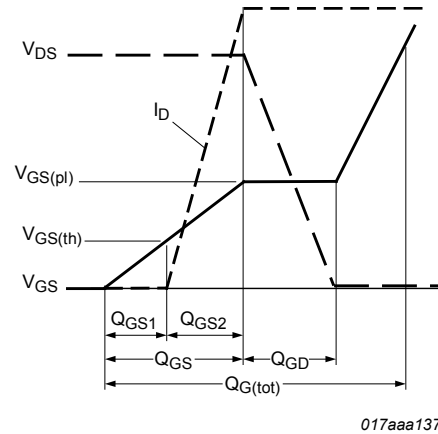
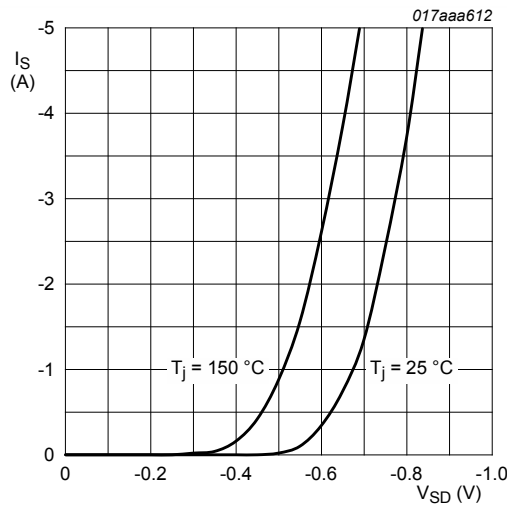


Fig. 15. MOSFET transistor: Gate charge waveform definitions



$V_{GS} = 0 \text{ V}$

Fig. 16. Source current as a function of source-drain voltage; typical values

## 11. Test information

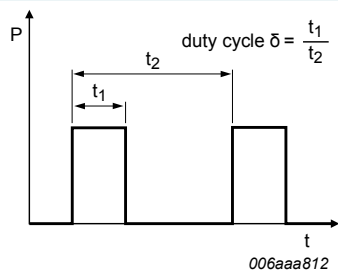


Fig. 17. Duty cycle definition

## 12. Package outline

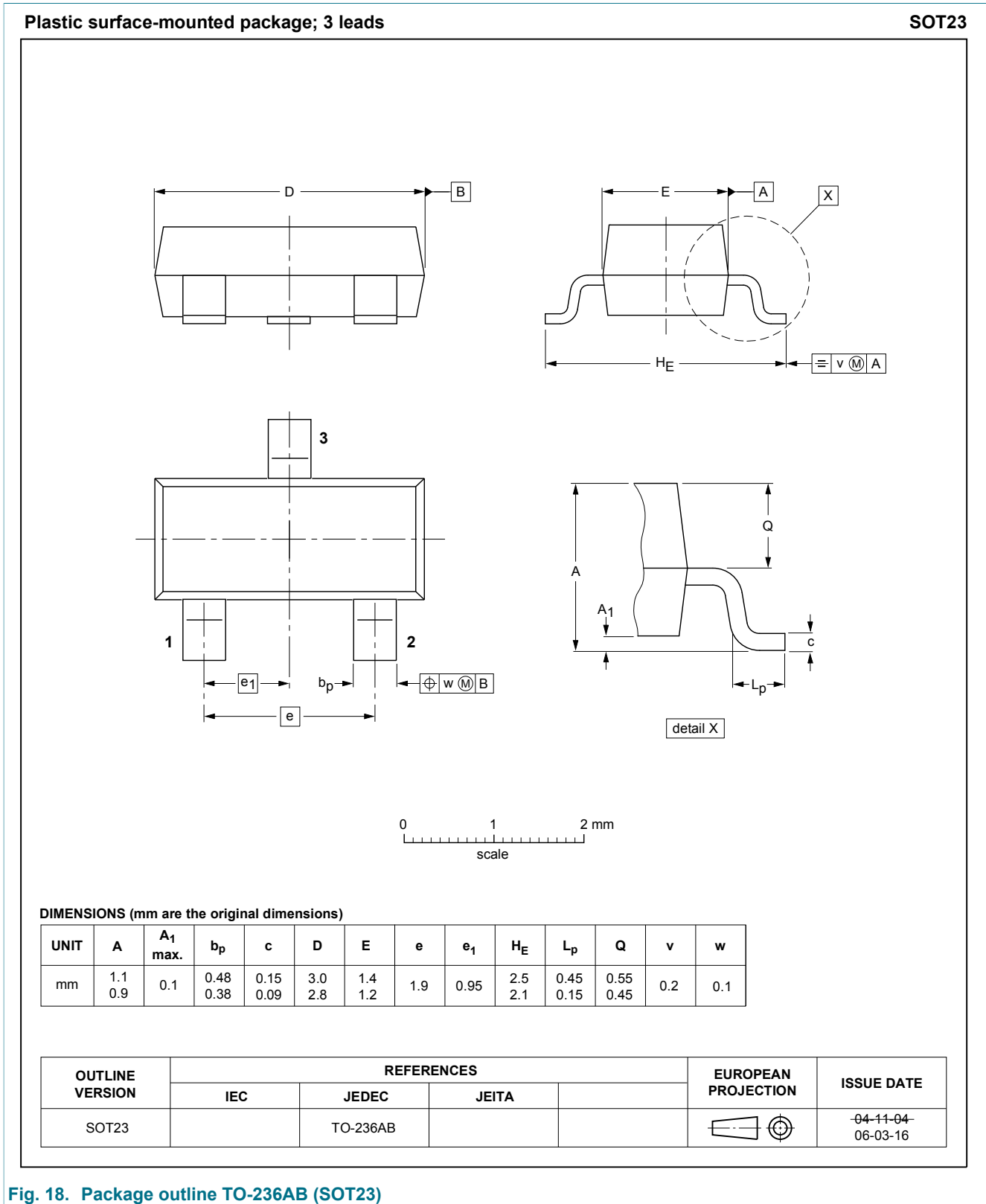


Fig. 18. Package outline TO-236AB (SOT23)

### 13. Soldering

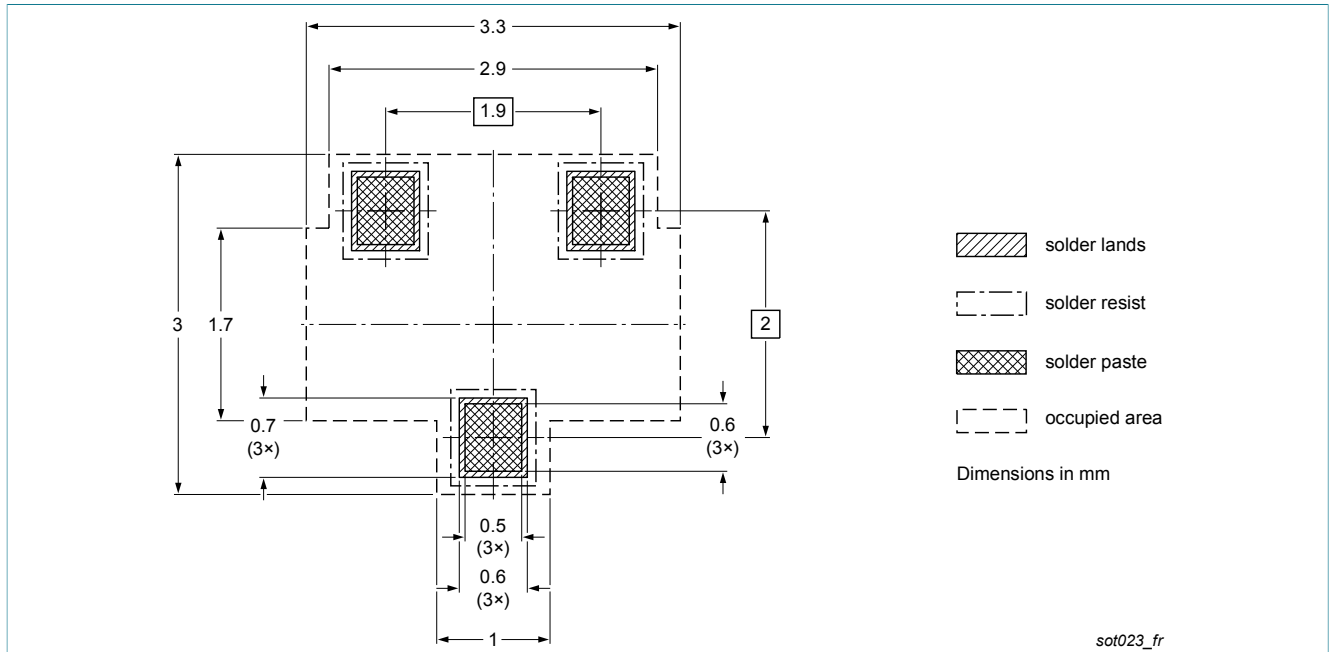


Fig. 19. Reflow soldering footprint for TO-236AB (SOT23)

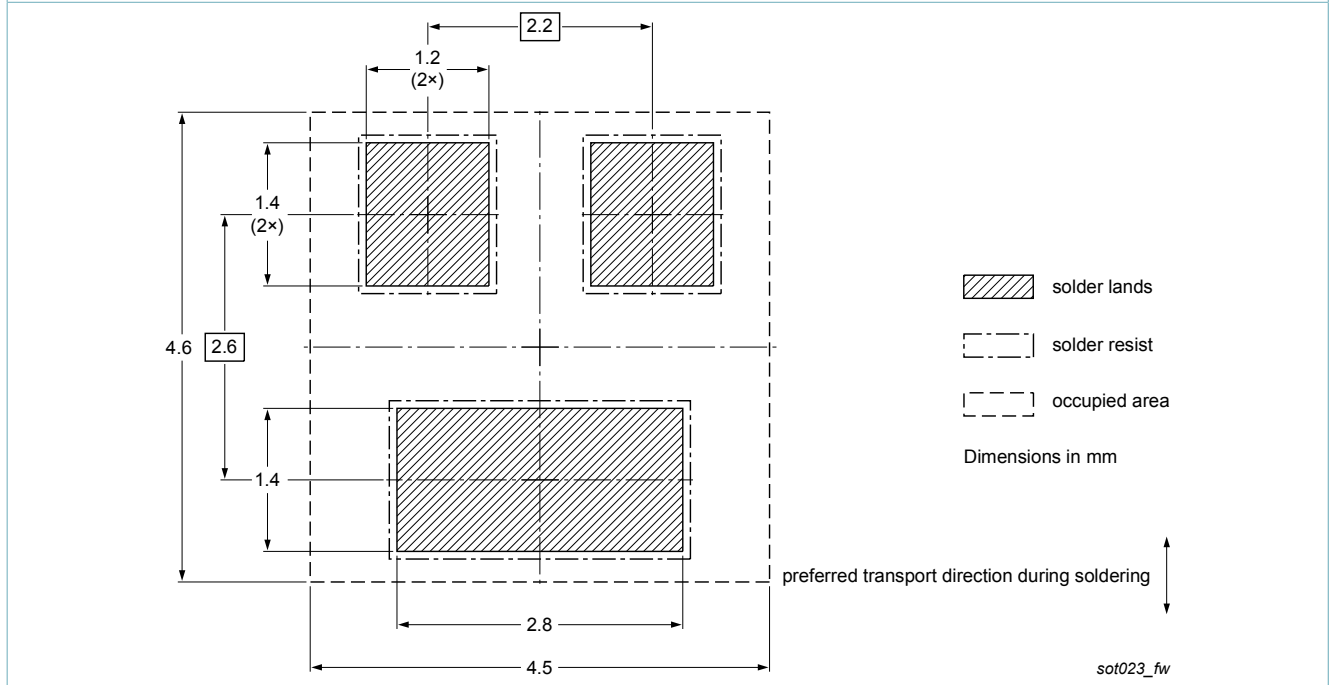


Fig. 20. Wave soldering footprint for TO-236AB (SOT23)

## 14. Revision history

Table 8. Revision history

| Data sheet ID | Release date | Data sheet status  | Change notice | Supersedes |
|---------------|--------------|--------------------|---------------|------------|
| PMV27UPE v.1  | 20140515     | Product data sheet | -             | -          |

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|--------------------------------|--------------------|---|
| Objective [short] data sheet   | Development        | This document contains data from the objective specification for product development. |
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| Product [short] data sheet     | Production         | This document contains the product specification.                                     |

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